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**PCN # 246**  
**Notification Date:**  
**March 14, 2023**

## Product / Process Change Notice

**Devices affected:**

The CBRDFSH1-100 Schottky bridge rectifier manufactured in the BR DFN case.

**Extent of change:**

Change in wafer fab, resulting in change in die size from 32 x 32 mils to 35 x 35 mils (see Table 1).

**Reason for change:**

As part of Central Semiconductor’s supply chain risk mitigation initiative, and in an effort to ensure an undisrupted supply of product, a change in wafer fabrication site is being made for the products referenced above. Product specifications, quality and reliability are not impacted by this change.

**Effect of change:**

This change does not affect the fit, form or function of the devices.

**Earliest effective date of change:**

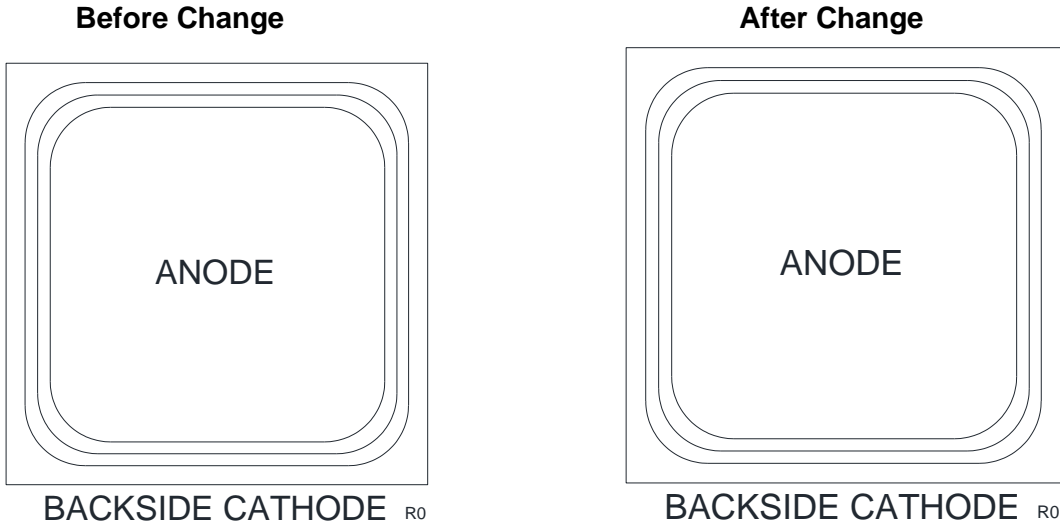
March 14, 2023

**Qualification data:**

Test	Condition	Failure rate
High Temperature Storage Life (HTSL)	150°C (-0/+10)°C, 1000 hours. JESD22-A103	0/77
Temperature Cycling (TC)	T= -65°C to +150°C 1000 cycles. Dwell time = 15 min. JESD22-A104 & MIL-STD-750 TM1051	0/77
High Temperature Reverse Bias (HTRB)	T=125°C, t=1000 hours, Bias per device data sheet JESD22-A108	0/77
Thermal Shock (TS)	100 cycles, dwell time = 5 min, -65°C to +150°C, max transfer time = 20 sec. JESD22-A106	0/77
Unbiased Highly Accelerated Temperature and Humidity Stress Test (UHAIST)	T = 110°C, RH = 85%, t = 264 hrs JESD22-A110	0/77
Highly Accelerated Temperature and Humidity Stress Test (HAST)	T = 110°C, RH = 85%, and t = 264 hours. Bias conditions per device specification sheet. JESD22-A110	0/77

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**Table 1:**



Die Size	32 x 32 MILS
Die Thickness	10 MILS
Anode Bonding Pad Size	29 x 29 MILS
Top Side Metalization	Ti/Ni/Ag
Back Side Metalization	Ti/Ni/Ag

Die Size	35 x 35 MILS
Die Thickness	11.8 MILS
Anode Bonding Pad Size	31.8 X 31.8 MILS
Top Side Metalization	TiW/TiNi/Ag
Back Side Metalization	Ti/Ni/Ag

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	